

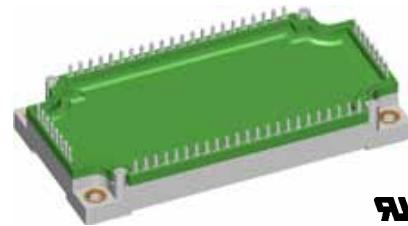
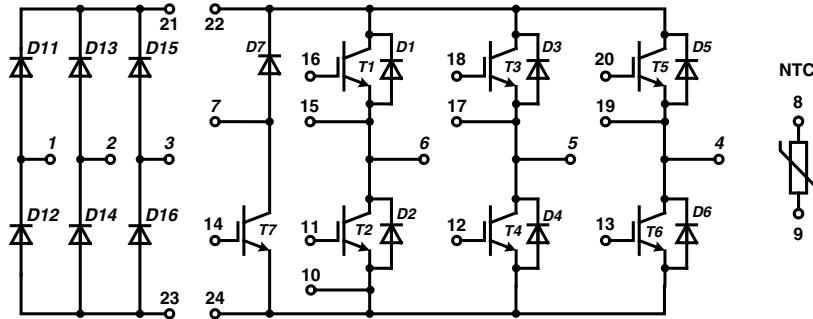
Converter - Brake - Inverter Module

XPT IGBT

Three Phase Rectifier	Brake Chopper	Three Phase Inverter
$V_{RRM} = 1600 \text{ V}$	$V_{CES} = 1200 \text{ V}$	$V_{CES} = 1200 \text{ V}$
$I_{DAVM} = 190 \text{ A}$	$I_{C25} = 60 \text{ A}$	$I_{C25} = 85 \text{ A}$
$I_{FSM} = 700 \text{ A}$	$V_{CE(sat)} = 1.8 \text{ V}$	$V_{CE(sat)} = 1.8 \text{ V}$

Part name (Marking on product)

MIXA60WB1200TEH



Pin configuration see outlines.

Features:

- Easy paralleling due to the positive temperature coefficient of the on-state voltage
- Rugged XPT design (Xtreme light Punch Through) results in:
 - short circuit rated for 10 μsec .
 - very low gate charge
 - square RBSOA @ 3x I_c
 - low EMI
- Thin wafer technology combined with the XPT design results in a competitive low $V_{CE(sat)}$
- SONIC™ diode
 - fast and soft reverse recovery
 - low operating forward voltage

Application:

- AC motor drives
- Solar inverter
- Medical equipment
- Uninterruptible power supply
- Air-conditioning systems
- Welding equipment
- Switched-mode and resonant-mode power supplies

Package:

- "E3-Pack" standard outline
- Insulated copper base plate
- Soldering pins for PCB mounting
- Temperature sense included

Output Inverter T1 - T6

Ratings						
Symbol	Definitions	Conditions	min.	typ.	max.	Unit
V_{CES}	collector emitter voltage	$T_{VJ} = 25^\circ C$		1200		V
V_{GES}	max. DC gate voltage			± 20		V
V_{GEM}	max. transient collector gate voltage	continuous transient		± 30		V
I_{C25}	collector current	$T_C = 25^\circ C$		85		A
I_{C80}		$T_C = 80^\circ C$		60		A
P_{tot}	total power dissipation	$T_C = 25^\circ C$		290		W
$V_{CE(sat)}$	collector emitter saturation voltage	$I_C = 55 A; V_{GE} = 15 V$	$T_{VJ} = 25^\circ C$ $T_{VJ} = 125^\circ C$	1.8 2.1	2.1	V
$V_{GE(th)}$	gate emitter threshold voltage	$I_C = 2 mA; V_{GE} = V_{CE}$	$T_{VJ} = 25^\circ C$	5.4	6.0	V
I_{CES}	collector emitter leakage current	$V_{CE} = V_{CES}; V_{GE} = 0 V$	$T_{VJ} = 25^\circ C$ $T_{VJ} = 125^\circ C$		0.5	mA
I_{GES}	gate emitter leakage current	$V_{GE} = \pm 20 V$			500	nA
$Q_{G(on)}$	total gate charge	$V_{CE} = 600 V; V_{GE} = 15 V; I_C = 50 A$		165		nC
$t_{d(on)}$	turn-on delay time	$T_{VJ} = 125^\circ C$ $V_{CE} = 600 V; I_C = 50 A$ $V_{GE} = \pm 15 V; R_G = 15 \Omega$		70		ns
t_r	current rise time			40		ns
$t_{d(off)}$	turn-off delay time			250		ns
t_f	current fall time			100		ns
E_{on}	turn-on energy per pulse			4.5		mJ
E_{off}	turn-off energy per pulse			5.5		mJ
RBSOA	reverse bias safe operating area	$V_{GE} = \pm 15 V; R_G = 15 \Omega;$ $V_{CEK} = 1200 V$	$T_{VJ} = 125^\circ C$		150	A
SCSOA	short circuit safe operating area					
t_{sc}	short circuit duration	$V_{CE} = 900 V; V_{GE} = \pm 15 V;$	$T_{VJ} = 125^\circ C$		10	μs
I_{sc}	short circuit current	$R_G = 15 \Omega$; non-repetitive		200		A
R_{thJC}	thermal resistance junction to case	(per IGBT)			0.43	K/W

Output Inverter D1 - D6

Ratings						
Symbol	Definitions	Conditions	min.	typ.	max.	Unit
V_{RRM}	max. repetitive reverse voltage	$T_{VJ} = 25^\circ C$		1200		V
I_{F25}	forward current	$T_C = 25^\circ C$		88		A
I_{F80}		$T_C = 80^\circ C$		59		A
V_F	forward voltage	$I_F = 60 A; V_{GE} = 0 V$	$T_{VJ} = 25^\circ C$ $T_{VJ} = 125^\circ C$	1.95 1.95	2.2	V
Q_{rr}	reverse recovery charge	$T_{VJ} = 125^\circ C$ $V_R = 600 V$ $di_F/dt = -1200 A/\mu s$ $I_F = 60 A; V_{GE} = 0 V$		8		μC
I_{RM}	max. reverse recovery current			60		A
t_{rr}	reverse recovery time			350		ns
E_{rec}	reverse recovery energy			2.5		mJ
R_{thJC}	thermal resistance junction to case	(per diode)			0.6	K/W

 $T_C = 25^\circ C$ unless otherwise stated

Brake T7

Symbol	Definitions	Conditions	Ratings			
			min.	typ.	max.	Unit
V_{CES}	collector emitter voltage	$T_{VJ} = 25^\circ C$		1200	1200	V
V_{GES}	max. DC gate voltage			± 20	± 20	V
V_{GEM}	max. transient collector gate voltage	continuous transient		± 30	± 30	V
I_{C25}	collector current	$T_C = 25^\circ C$		60	60	A
I_{C80}		$T_C = 80^\circ C$		40	40	A
P_{tot}	total power dissipation	$T_C = 25^\circ C$		200	200	W
$V_{CE(sat)}$	collector emitter saturation voltage	$I_C = 35 A; V_{GE} = 15 V$	$T_{VJ} = 25^\circ C$ $T_{VJ} = 125^\circ C$	1.8 2.1	2.1	V
$V_{GE(th)}$	gate emitter threshold voltage	$I_C = 1.5 mA; V_{GE} = V_{CE}$	$T_{VJ} = 25^\circ C$	5.4	6.0	V
I_{CES}	collector emitter leakage current	$V_{CE} = V_{CES}; V_{GE} = 0 V$	$T_{VJ} = 25^\circ C$ $T_{VJ} = 125^\circ C$		0.5	mA
I_{GES}	gate emitter leakage current	$V_{GE} = \pm 20 V$			500	nA
$Q_{G(on)}$	total gate charge	$V_{CE} = 600 V; V_{GE} = 15 V; I_C = 35 A$		107		nC
$t_{d(on)}$	turn-on delay time	$V_{CE} = 600 V; I_C = 35 A$ $V_{GE} = \pm 15 V; R_G = 27 \Omega$	$T_{VJ} = 125^\circ C$	70		ns
t_r	current rise time			40		ns
$t_{d(off)}$	turn-off delay time			250		ns
t_f	current fall time			100		ns
E_{on}	turn-on energy per pulse			3.8		mJ
E_{off}	turn-off energy per pulse			4.1		mJ
RBSOA	reverse bias safe operating area	$V_{GE} = \pm 15 V; R_G = 27 \Omega;$ $V_{CEK} = 1200 V$	$T_{VJ} = 125^\circ C$		105	A
SCSOA	short circuit safe operating area					
t_{sc}	short circuit duration	$V_{CE} = 900 V; V_{GE} = \pm 15 V;$ $R_G = 27 \Omega$; non-repetitive	$T_{VJ} = 125^\circ C$	10	μs	
I_{sc}	short circuit current			140	A	
R_{thJC}	thermal resistance junction to case	(per IGBT)		0.64	K/W	

Brake Chopper D7

Symbol	Definitions	Conditions	Ratings			
			min.	typ.	max.	Unit
V_{RRM}	max. repetitive reverse voltage	$T_{VJ} = 25^\circ C$		1200	1200	V
I_{F25}	forward current	$T_C = 25^\circ C$		44	44	A
I_{F80}		$T_C = 80^\circ C$		29	29	A
V_F	forward voltage	$I_F = 30 A; V_{GE} = 0 V$	$T_{VJ} = 25^\circ C$ $T_{VJ} = 125^\circ C$	1.95 1.95	2.2	V
I_R	reverse current	$V_R = V_{RRM}$	$T_{VJ} = 25^\circ C$ $T_{VJ} = 125^\circ C$	0.8	2.0	mA
Q_{rr}	reverse recovery charge	$V_R = 600 V$ $dI_F/dt = 600 A/\mu s$ $I_F = 30 A; V_{GE} = 0 V$	$T_{VJ} = 125^\circ C$	3.5		μC
I_{RM}	max. reverse recovery current			30		A
t_{rr}	reverse recovery time			350		ns
E_{rec}	reverse recovery energy			0.9		mJ
R_{thJC}	thermal resistance junction to case	(per diode)		1.2	K/W	

 $T_C = 25^\circ C$ unless otherwise stated

Input Rectifier Bridge D11 - D16

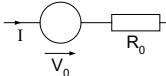
Ratings						
Symbol	Definitions	Conditions	min.	typ.	max.	Unit
V_{RRM}	max. repetitive reverse voltage	$T_{VJ} = 25^\circ C$		1600		V
I_{FAV}	average forward current	sine 180°	$T_C = 80^\circ C$	70		A
I_{DAVM}	max. average DC output current	rect.; $d = 1/3$	$T_C = 80^\circ C$	190		A
I_{FSM}	max. forward surge current	$t = 10 \text{ ms}; \text{sine } 50 \text{ Hz}$	$T_{VJ} = 25^\circ C$ $T_{VJ} = 125^\circ C$	700 620		A
I^2t	I^2t value for fusing	$t = 10 \text{ ms}; \text{sine } 50 \text{ Hz}$	$T_{VJ} = 25^\circ C$ $T_{VJ} = 125^\circ C$	1920 2450		A ² s
P_{tot}	total power dissipation		$T_C = 25^\circ C$	192		W
V_F	forward voltage	$I_F = 80 \text{ A}$	$T_{VJ} = 25^\circ C$ $T_{VJ} = 125^\circ C$	1.2 1.2	1.5	V
I_R	reverse current	$V_R = V_{RRM}$	$T_{VJ} = 25^\circ C$ $T_{VJ} = 125^\circ C$	0.05 1.5	0.1	mA
R_{thJC}	thermal resistance junction to case	(per diode)			0.65	K/W

Temperature Sensor NTC

Ratings						
Symbol	Definitions	Conditions	min.	typ.	max.	Unit
R_{25}	resistance	$T_C = 25^\circ C$	4.75	5.0	5.25	kΩ
$B_{25/50}$			3375			K

Module

Ratings						
Symbol	Definitions	Conditions	min.	typ.	max.	Unit
T_{VJ}	operating temperature		-40		125	°C
T_{VJM}	max. virtual junction temperature				150	°C
T_{stg}	storage temperature		-40		125	°C
V_{ISOL}	isolation voltage	$I_{ISOL} \leq 1 \text{ mA}; 50/60 \text{ Hz}$			3000	V~
CTI	comparative tracking index				-	
M_d	mounting torque (M5)		3		6	Nm
d_s	creep distance on surface		6			mm
d_A	strike distance through air		6			mm
$R_{pin-chip}$	resistance pin to chip			5		mΩ
R_{thCH}	thermal resistance case to heatsink	with heatsink compound		0.01		K/W
Weight				300		g

Equivalent Circuits for Simulation

Ratings						
Symbol	Definitions	Conditions	min.	typ.	max.	Unit
V_0	rectifier diode	D8 - D13	$T_{VJ} = 150^\circ C$		0.85	V
R_0					3.9	mΩ
V_0	IGBT	T1 - T6	$T_{VJ} = 150^\circ C$		1.1	V
R_0					25.1	mΩ
V_0	free wheeling diode	D1 - D6	$T_{VJ} = 150^\circ C$		1.22	V
R_0					13	mΩ
V_0	IGBT	T7	$T_{VJ} = 150^\circ C$		1.1	V
R_0					40	mΩ
V_0	free wheeling diode	D7	$T_{VJ} = 150^\circ C$		1.2	V
R_0					27.0	mΩ

 $T_C = 25^\circ C$ unless otherwise stated

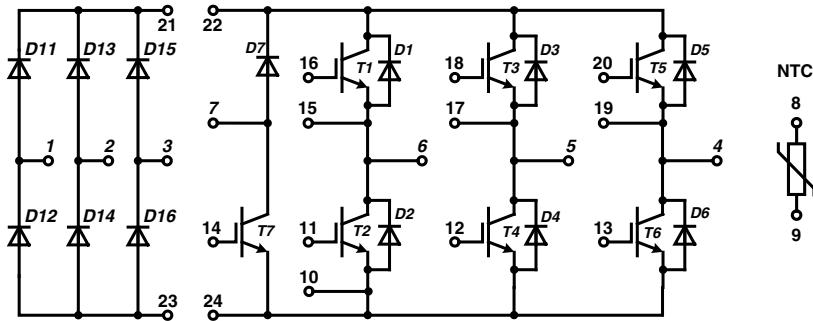
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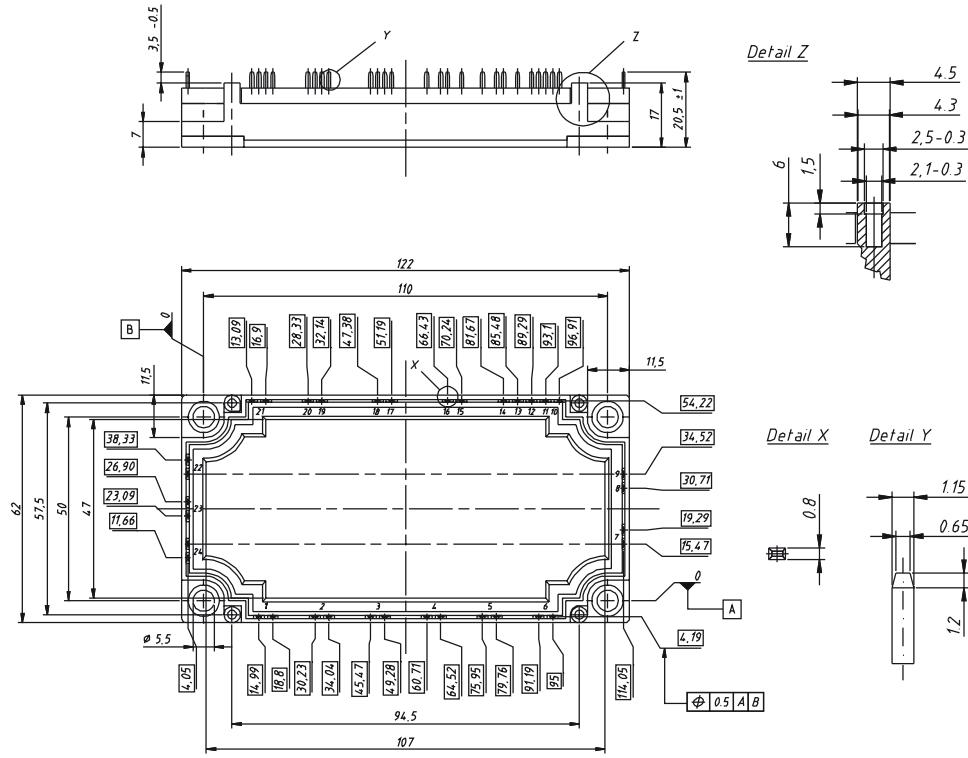
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Circuit Diagram

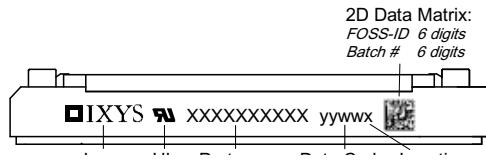


Outline Drawing

Dimensions in mm (1 mm = 0.0394")



Product Marking



2D Data Matrix:
FOSS-ID 6 digits
Batch # 6 digits

Part number

M = Module
I = IGBT
XA = XPT standard
60 = Current Rating [A]
WB = 6-Pack + 3~ Rectifier Bridge & Brake Unit
1200 = Reverse Voltage [V]
T = NTC
EH = E3-Pack

Ordering	Part Name	Marking on Product	Delivering Mode	Base Qty	Ordering Code
Standard	MIXA60WB1200 TEH	MIXA60WB1200TEH	Box	5	507653

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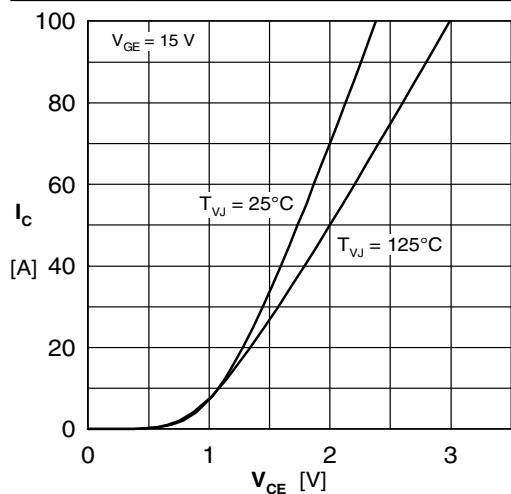
Inverter T1 - T6


Fig. 1 Typ. output characteristics

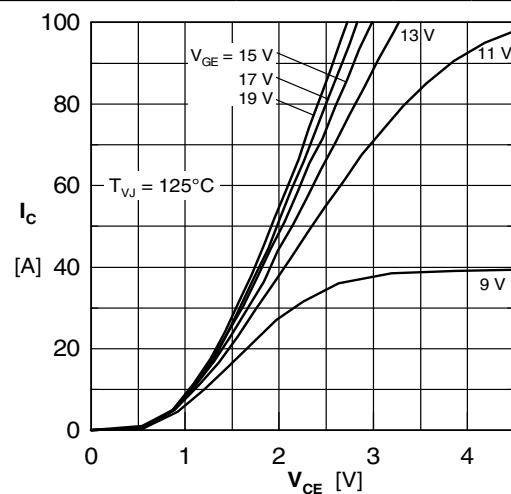


Fig. 2 Typ. output characteristics

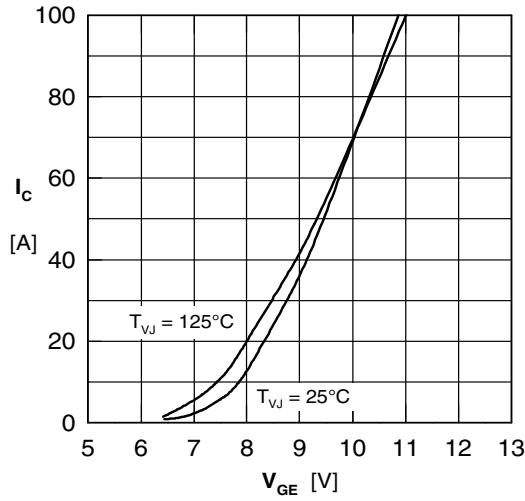


Fig. 3 Typ. tranfer characteristics

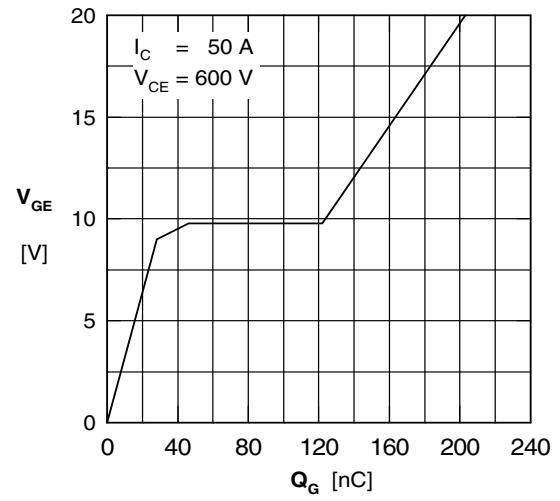


Fig. 4 Typ. turn-on gate charge

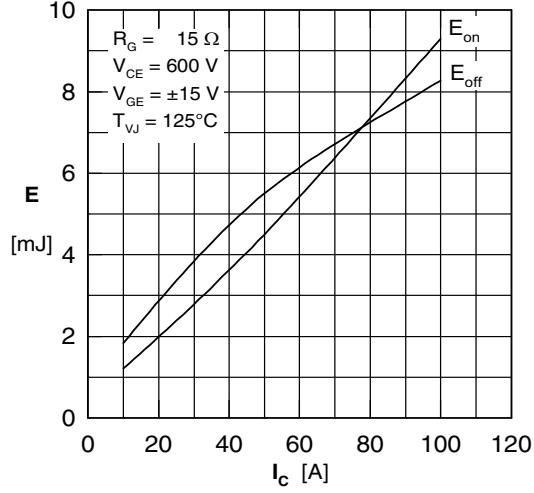


Fig. 5 Typ. switching energy vs. collector current

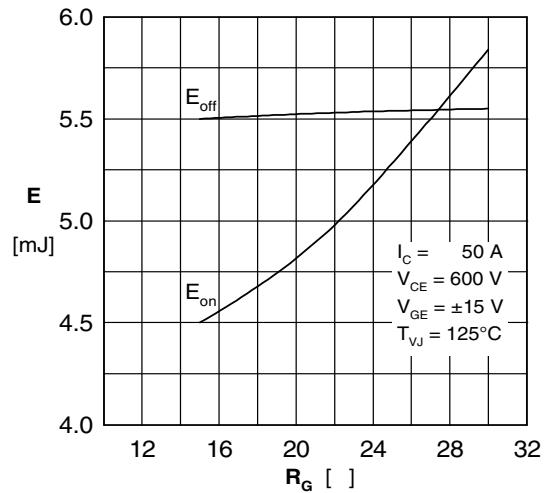


Fig. 6 Typ. switching energy vs. gate resistance

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Inverter D1 - D6

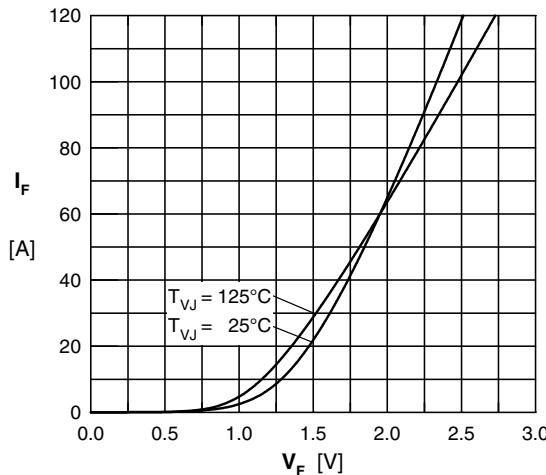
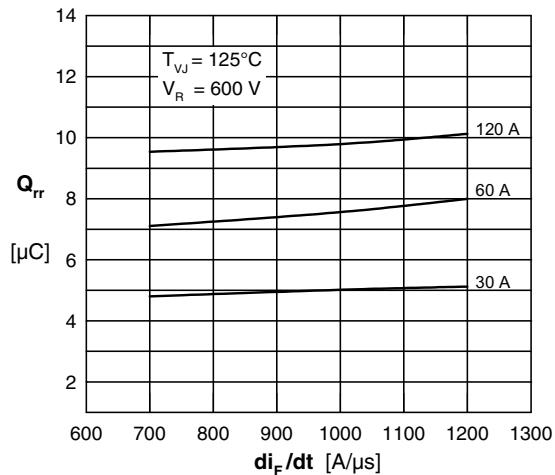
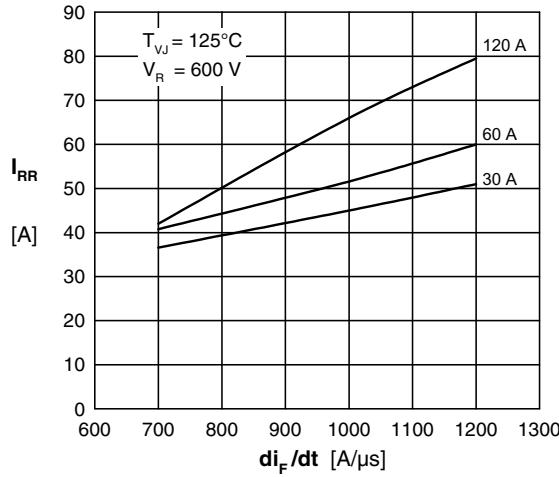
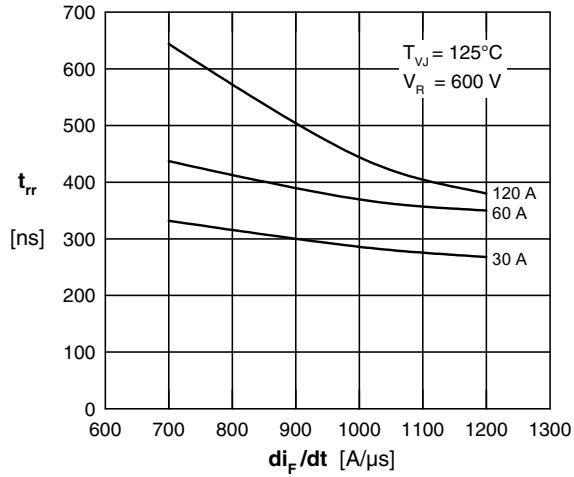
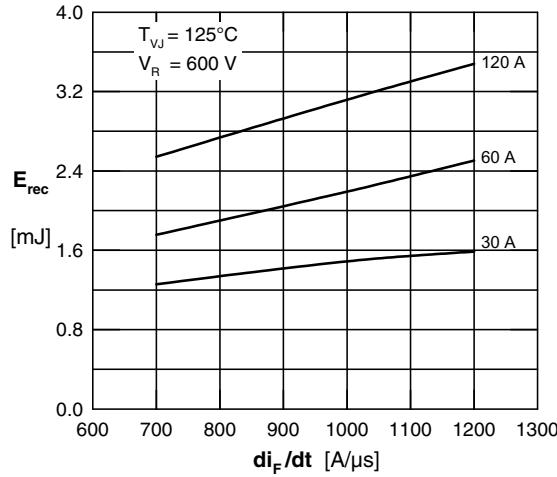
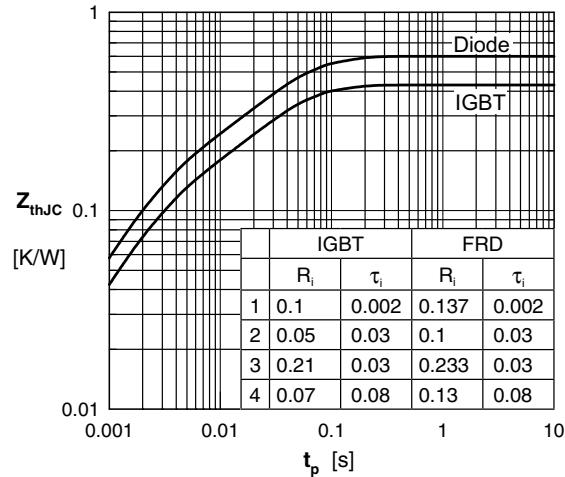
Fig. 7 Typ. Forward current versus V_F Fig. 8 Typ. reverse recov.charge Q_{rr} vs. di/dt Fig. 9 Typ. peak reverse current I_{rr} vs. di/dt Fig. 10 Typ. recovery time t_{rr} versus di/dt Fig. 8 Typ. recovery energy E_{rec} versus di/dt 

Fig. 9 Typ. transient thermal impedance

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Brake T7 & D7

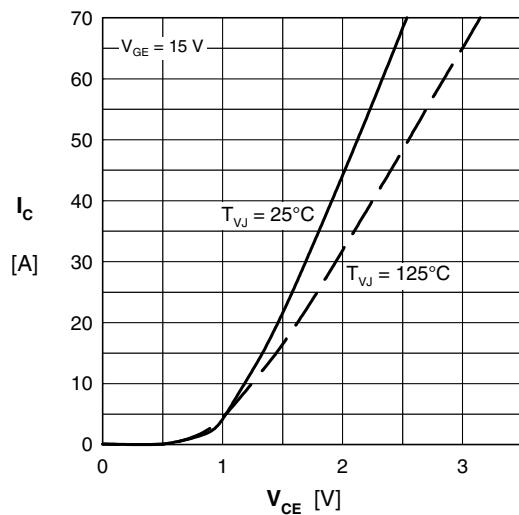


Fig. 13 Typ. output characteristics

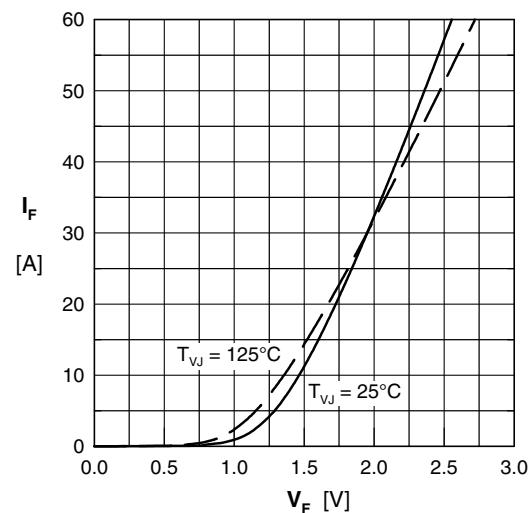


Fig. 14 Typ. forward characteristics

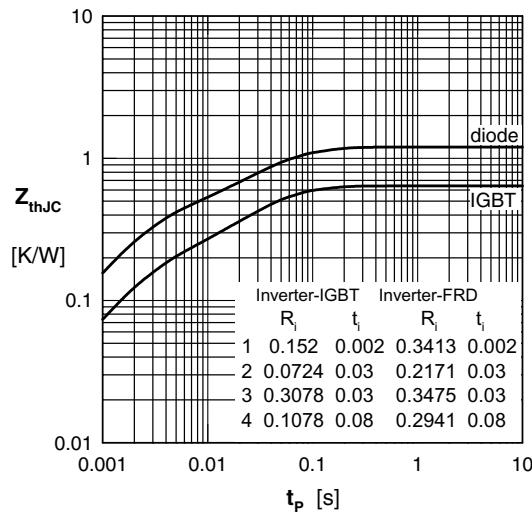


Fig. 15 Typ. transient thermal impedance

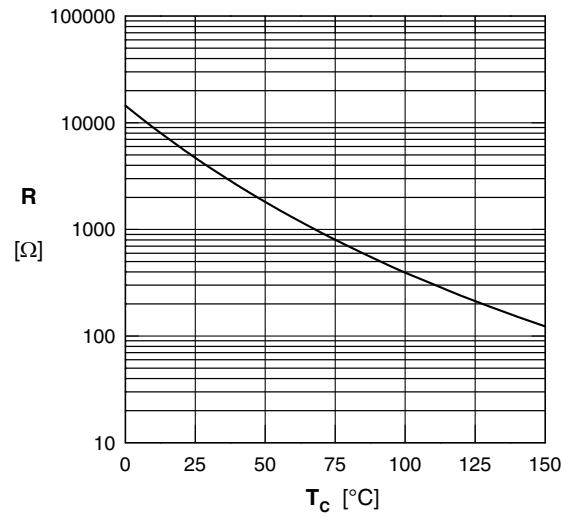


Fig. 16 Typ. NTC resistance vs. temperature